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MARGER JOHNSON & MCCOLLOM, P.C. 1030 SW MORRISON STREET PORTLAND, OR 97205			EXAMINER WILLIAMS, ALEXANDER O	
			ART UNIT 2826	PAPER NUMBER

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Please find below and/or attached an Office communication concerning this application or proceeding.



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Serial Number: 10/651813 Attorney's Docket #: 9903-078

Filing Date: 8/28/2003; claimed foreign priority to 7/10/2001 and 1/18/2002

Applicant: Song et al.

Examiner: Alexander Williams

Applicant's Amendment filed 11/1/04 has been acknowledged.

Applicant's election of the species of figure 18 (claims 1, 3, 4, 6-11, 24-30, 33, 34, 36-38, 40, 42 and 46), filed 5/3/2004, has been acknowledged.

This application contains claims 2, 5, 12-23, 31, 32, 35, 39, 41 and 43-45 drawn to an invention non-elected with traverse. Applicant's attempt to cancel the non-elected claims was not in proper form. Within the listing of the claims, indication of desired claim to be canceled should be performed.

Acknowledgment is made of applicant's claim for foreign priority based on an application filed in Republic of Korea on 7/10/2001 and 1/18/2002. It is noted, however, that applicant has not filed a certified copy of the foreign application as required by 35 U.S.C. 119(b).

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein

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were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(f) or (g) prior art under 35 U.S.C. 103(a).

Claims 1, 3, 4, 6, 8-11, 24-30, 33, 34, 36-38, 40, 42 and 46 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Pai et al. (U.S. Patent # 6,503,776 B2) in view of Akram et al. (U.S. Patent # 6,228,687 B1).

1. Pai et al. (figures 110) specifically figure 8 show a semiconductor multi-chip package comprising: a package substrate **120** including a surface having a plurality of bonding tips **120a** formed thereon; and two or more semiconductor chips **110,130** mounted on the substrate surface. Pai et al. fail to explicitly show the two or more semiconductor chips each including: a semiconductor substrate having integrated circuits formed on a cell region and a peripheral circuit region adjacent to each other; a bond pad-wiring pattern formed on the semiconductor substrate; and a pad-rearrangement pattern electrically connected to the bond pad-wiring pattern, the pad-rearrangement pattern including bond pads disposed over at least a part of the cell region, wherein the bond pad-wiring pattern is formed substantially in a center region of the semiconductor substrate, wherein each bonding tip is electrically connected to a corresponding one of the bond pads, wherein each bonding tip is electrically connected to a corresponding one of the bond pads.

Akram et al. is cited for showing a wafer-level package. Specifically, Akram et al. (figures 1 to 10) specifically figures 8A and 8B discloses semiconductor chip **210** each including: a semiconductor substrate **212** having integrated circuits formed on a cell region (within 212) and a peripheral circuit region adjacent to each other; a bond pad-wiring pattern **216** formed on the semiconductor substrate; and a pad-rearrangement pattern **222** electrically connected to the bond pad-wiring pattern, the pad-rearrangement pattern including bond pads **221** disposed over at least a part of the cell region, wherein the bond pad-wiring pattern is formed substantially in a center region of the semiconductor substrate for the purpose of forming a desired semiconductor integrated circuit in the internal circuit region for a semiconductor integrated circuit device.

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(22) FIGS. 8A and 8B illustrate another embodiment of a chip-scale package 210, which includes a semiconductor device 212 and a carrier substrate 218 disposed adjacent an active surface 214 of semiconductor device 212.

(23) As illustrated, semiconductor device 212 is a leads over chip ("LOC") type semiconductor device, which includes bond pads 216 disposed substantially linearly across the center of semiconductor device 212. A conductive bump 217 may be disposed on each bond pad 216 or on a BLM or UBM structure adjacent to each bond pad 216.

(24) Carrier substrate 218 comprises an insulative layer 220, preferably formed of polymeric material, such as polyimide or another non-conductive elastomer, and has a substantially consistent thickness. Bond pads 216 of semiconductor device 212 or conductive bumps 217 are exposed through layer 220 through one or more apertures 228. An adhesive film layer 230 is disposed adjacent layer 220, opposite semiconductor device 212. Adhesive film layer 230 carries conductive traces 222 and external package bumps 224. External package bumps 224 protrude from adhesive film layer 230. Conductive traces 222 are in electrical communication with corresponding external package bumps 224 and extend across adhesive film layer 230 to corresponding vias 221. Vias 221, which communicate with conductive traces 222, extend through adhesive film layer 230, into apertures 228, and into electrical communication with corresponding bond pads 216.

(25) As illustrated in FIGS. 8A and 8B, each conductive trace 222 communicates with a corresponding external package bump 224. Thus, each bond pad 216 that communicates with a conductive trace 222 may also communicate with a laterally offset, corresponding external package bump 224. Alternatively, as illustrated in FIG. 8C, each conductive trace 222 may communicate with a group or an array of external package bumps 224.

(26) FIG. 8D illustrates a variation of chip-scale package 210', which includes a semiconductor device 212' having peripherally located bond pads 216' and external package bumps 224' disposed in an array on adhesive film layer 230'.

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3. The multi-chip package of claim 1, the combination with Pai et al. showing wherein the two or more chips are vertically stacked.
4. The multi-chip package of claim 1, the combination with Pai et al. showing wherein the two or more chips comprise the same type of chips.
6. The multi-chip package of claim 1, the combination with Pia et al. wherein one of the two or more chips is a memory chip and the other chip is a non-memory chip (see column 1, lines 5-32).
8. The multi-chip package of claim 1, the combination with Akram et al. showing wherein the bond pads are formed along sides of the semiconductor substrate.
9. The multi-chip package of claim 1, the combination with Akram et al. showing wherein a portion of the pad-rearrangement pattern extends substantially from the center region of the semiconductor substrate toward an edge of the semiconductor substrate.
10. The multi-chip package of claim 1, the combination with Akram et al. showing wherein the bond pad-wiring pattern is formed on a portion of the peripheral circuit region and extends across a portion of the cell region.
11. The multi-chip package of claim 1, the combination with Akram et al. showing wherein the bond pad-wiring pattern is formed entirely within the peripheral circuit region.
24. Pai et al. (figures 110) specifically figure 8 show a multi-chip package comprising: a first chip **110**; and a second chip **130** formed over the first chip. Pai et al. fail to explicitly show the first chip includes: a bond pad-wiring pattern formed substantially in a center region of the first chip; and a pad-rearrangement pattern electrically connected to the bond pad-wiring pattern, wherein the pad-rearrangement pattern includes a first bond pad disposed at an edge of the first chip.

Akram et al. is cited for showing a wafer-level package. Specifically, Akram et al. (figures 1 to 10) specifically figures 8A and 8B discloses semiconductor chip **210** each including: a semiconductor substrate **212** having integrated circuits formed on a cell region (within 212) and a peripheral circuit region adjacent to each other; a bond pad-wiring pattern **216** formed on the semiconductor substrate; and a pad-rearrangement pattern **222** electrically connected to the bond pad-wiring pattern, the pad-rearrangement pattern including bond pads **221** disposed over at least a part of the cell region, wherein the bond pad-wiring pattern is formed substantially in a center region of

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the semiconductor substrate for the purpose of forming a desired semiconductor integrated circuit in the internal circuit region for a semiconductor integrated circuit device.

25. The multi-chip package of claim 24, the combination with Akram et al. showing wherein the pad-rearrangement pattern includes a second bond pad, and wherein the first and second bond pads are respectively disposed along opposing edges of the first chip.

26. The multi-chip package of claim 25, the combination with Akram et al. showing wherein the pad-rearrangement pattern extends substantially from the center region of the first chip toward the edge of the first chip.

27. The multi-chip package of claim 24, the combination with Akram et al. showing wherein the bond pad-wiring pattern is formed on a first surface of the first chip, and Pai et al. show wherein the second chip is mounted on the first surface of the first chip.

28. The multi-chip package of claim 27, the combination with Pai et al. showing further comprising a spacer **160** interposed between the first chip and the second chip.

29. The multi-chip package of claim 24, the combination with Pai et al. showing further comprising a substrate **120** on which the first chip is mounted.

30. The multi-chip package of claim 29, the combination with Pai et al. showing wherein the substrate **120** comprises a printed circuit board, a tape wiring substrate or a lead frame.

33. The multi-chip package of claim 24, the combination show wherein the first bond pad is disposed under the second chip. It is unclear what is claimed here.

34. The multi-chip package of claim 24, the combination with Pai et al. showing wherein the first **110** and second **130** chips comprise the same type of chips.

36. Pai et al. (figures 110) specifically figure 8 show a multi-chip package comprising: a first chip **110**; and a second chip **130** formed over the first chip **110**. Pai et al. fail to explicitly show wherein the second chip includes: a second bond pad-wiring pattern formed substantially in a center region of the second chip; and a second pad-rearrangement pattern electrically connected to the second bond pad-wiring pattern, wherein the second pad-rearrangement pattern includes a second bond pad disposed at an edge of the second chip.

Akram et al. is cited for showing a wafer-level package. Specifically, Akram et al. (figures 1 to 10) specifically figures 8A and 8B discloses semiconductor chip **210** each

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including: a semiconductor substrate **212** having integrated circuits formed on a cell region (within 212) and a peripheral circuit region adjacent to each other; a bond pad-wiring pattern **216** formed on the semiconductor substrate; and a pad-rearrangement pattern **222** electrically connected to the bond pad-wiring pattern, the pad-rearrangement pattern including bond pads **221** disposed over at least a part of the cell region, wherein the bond pad-wiring pattern is formed substantially in a center region of the semiconductor substrate for the purpose of forming a desired semiconductor integrated circuit in the internal circuit region for a semiconductor integrated circuit device.

37. The multi-chip package of claim 36, the combination with Pia et al. showing wherein the first chip includes; a first bond pad-wiring pattern formed substantially in a center region of the first chip; and a first pad-rearrangement pattern electrically connected to the first bond pad-wiring pattern, wherein the first pad-rearrangement pattern includes a first bond pad disposed at an edge of the first chip.

38. The multi-chip package of claim 37, the combination with Akram et al. showing wherein the first bond pad-wiring pattern is formed on a first surface of the first chip, and wherein the second chip is mounted on the first surface of the first chip.

40. The multi-chip package of claim 36, Pai et al. further comprising a substrate **120** on which the first chip is mounted.

42. The multi-chip package of claim 40, the combination with Akram et al. showing wherein the first chip includes a center pad-type bond pad.

46. (but really claim 47). Pai et al. (figures 110) specifically figure 8 show a semiconductor multi-chip package comprising: a first chip **110** mounted on a package substrate; and an second chip **130** mounted on the first chip with a spacer **160** disposed therebetween, wherein the spacer is placed between the bond pads.

Pai et al. fail to explicitly show wherein the first chip includes; bond pad-wiring patterns formed substantially in a center region of the first chip; and pad-rearrangement patterns electrically connected to the bond pad-wiring patterns, wherein the pad-rearrangement patterns include bond pads disposed along opposing edges of the first chip.

Akram et al. is cited for showing a wafer-level package. Specifically, Akram et al. (figures 1 to 10) specifically figures 8A and 8B discloses semiconductor chip **210** each

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including: a semiconductor substrate **212** having integrated circuits formed on a cell region (within 212) and a peripheral circuit region adjacent to each other; a bond pad-wiring pattern **216** formed on the semiconductor substrate; and a pad-rearrangement pattern **222** electrically connected to the bond pad-wiring pattern, the pad-rearrangement pattern including bond pads **221** disposed over at least a part of the cell region, wherein the bond pad-wiring pattern is formed substantially in a center region of the semiconductor substrate for the purpose of forming a desired semiconductor integrated circuit in the internal circuit region for a semiconductor integrated circuit device.

Therefore, it would have been obvious to one of ordinary skill in the art to use Akram et al.'s internal structure of a chip to modify Pai et al.'s chip for the purpose of forming a desired semiconductor integrated circuit in the internal circuit region for a semiconductor integrated circuit device.

Claim 6 is rejected under 35 U.S.C. § 103(a) as being unpatentable over Pai et al. (U.S. Patent # 6,503,776 B2) in view of Akram et al. (U.S. Patent # 6,228,687 B1) and further in view of Hsuan et al. (U.S. Patent # 6,239,366 B1).

The combination of Akram et al. and Pai et al. show the features of the claimed invention as detailed, but fail to explicitly show one of the two or more chips is a DRAM and the other chip is a flash memory.

Hsuan et al. is cited for showing a face to face multi-chip package. Specifically, Hsuan et al. (figures 3A to 5D) specifically figure 3a discloses stacked dies, wherein one of the two or more chips is a DRAM and the other chip is a flash memory for the purpose of providing multi-chip packages to enhance the performance of the chips.

In a multi-chip package, chips of processor, memory, including dynamic random access memory (DRAM) and flash memory, and logic circuit can be packed together in a single package to reduce the fabrication cost and the packaging volume. Furthermore, the signal transmission path is shortened to enhance the efficiency.

Therefore, it would have been obvious to one of ordinary skill in the art to use Huang et al.'s a DRAM and the other chip is a flash memory and Akram et al.'s internal structure of a chip to modify Pai et al.'s chip for the purpose of forming a desired semiconductor integrated circuit in the internal circuit region for a semiconductor integrated circuit device.

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## Response

Applicant's arguments filed 11/1/04 have been fully considered, but are moot in view of the new grounds of rejections detailed above.

The listed references are cited as of interest to this application, but not applied at this time.

Field of Search	Date
U.S. Class and subclass: 257/686,685,734,777,784,786,728,724,725,698,690,203, 211,208	6/24/04 1/22/05
Other Documentation: foreign patents and literature in 257/686,685,734,777,784,786,728,724,725,698,690,203, 211,208	6/24/04 1/22/05
Electronic data base(s): U.S. Patents EAST	6/24/04 1/22/05

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Alexander O Williams whose telephone number is (571) 272 1924. The examiner can normally be reached on M-F 6:30-7:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (571) 272 1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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AOW  
1/23/05



Primary Patent Examiner  
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